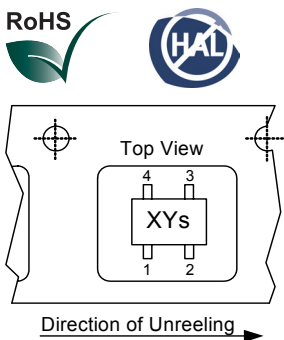
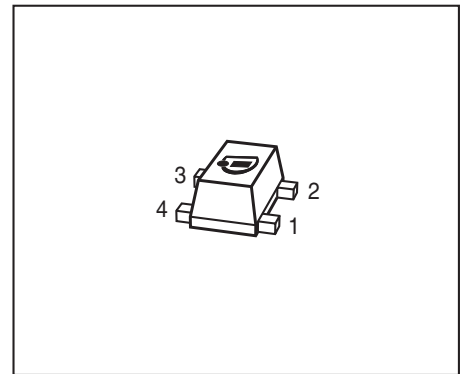


**Linear Low Noise SiGe:C Bipolar RF Transistor**

- For medium power amplifiers and driver stages
- Based on Infineon' s reliable high volume Silicon Germanium technology
- High  $OIP3$  and  $P_{-1dB}$
- Ideal for low phase noise oscillators
- Maxim. available Gain  $G_{ma} = 21.5$  dB at 1.8 GHz  
Minimum noise figure  $NF_{min} = 0.8$  dB at 1.8 GHz
- Pb-free (RoHS compliant) and halogen-free thin small flat package with visible leads
- Qualification report according to AEC-Q101 available



**ESD (Electrostatic discharge) sensitive device, observe handling precaution!**

Type	Marking	Pin Configuration						Package
BFP650F	R5s	1=B	2=E	3=C	4=E	-	-	TSFP-4

**Maximum Ratings** at  $T_A = 25\text{ °C}$ , unless otherwise specified

Parameter	Symbol	Value	Unit
Collector-emitter voltage $T_A = 25\text{ °C}$ $T_A = -55\text{ °C}$	$V_{CEO}$	4 3.7	V
Collector-emitter voltage	$V_{CES}$	13	
Collector-base voltage	$V_{CBO}$	13	
Emitter-base voltage	$V_{EBO}$	1.2	
Collector current	$I_C$	150	mA
Base current	$I_B$	10	
Total power dissipation <sup>1)</sup> $T_S \leq 85\text{ °C}$	$P_{tot}$	500	mW
Junction temperature	$T_J$	150	°C
Storage temperature	$T_{Stg}$	-55 ... 150	

**Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>2)</sup>	$R_{thJS}$	130	K/W

**Electrical Characteristics** at  $T_A = 25\text{ °C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Collector-emitter breakdown voltage $I_C = 3\text{ mA}$ , $I_B = 0$	$V_{(BR)CEO}$	4	4.5	-	V
Collector-emitter cutoff current $V_{CE} = 13\text{ V}$ , $V_{BE} = 0$	$I_{CES}$	-	-	100	$\mu\text{A}$
Collector-base cutoff current $V_{CB} = 5\text{ V}$ , $I_E = 0$	$I_{CBO}$	-	-	100	nA
Emitter-base cutoff current $V_{EB} = 0.5\text{ V}$ , $I_C = 0$	$I_{EBO}$	-	-	10	$\mu\text{A}$
DC current gain $I_C = 80\text{ mA}$ , $V_{CE} = 3\text{ V}$ , pulse measured	$h_{FE}$	110	180	270	-

<sup>1</sup> $T_S$  is measured on the emitter lead at the soldering point to the pcb

<sup>2</sup>For the definition of  $R_{thJS}$  please refer to Application Note AN077 (Thermal Resistance Calculation)

**Electrical Characteristics at  $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified**

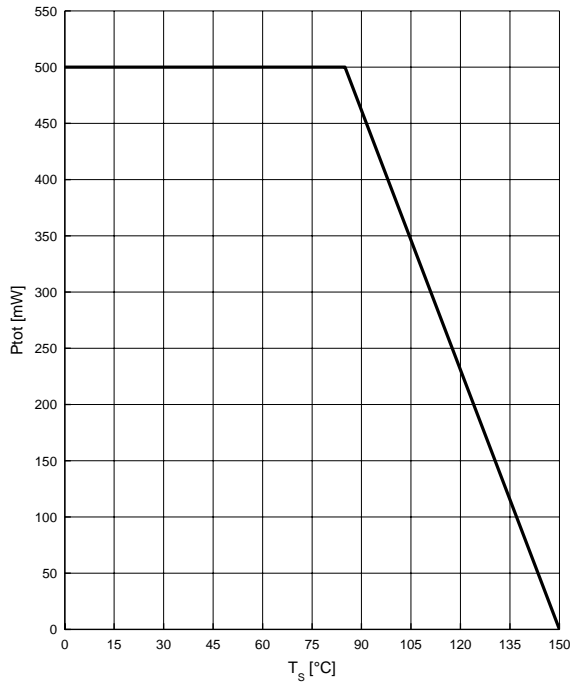
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>AC Characteristics (verified by random sampling)</b>					
Transition frequency $I_C = 80\text{ mA}$ , $V_{CE} = 3\text{ V}$ , $f = 1\text{ GHz}$	$f_T$	-	42	-	GHz
Collector-base capacitance $V_{CB} = 3\text{ V}$ , $f = 1\text{ MHz}$ , $V_{BE} = 0$ , emitter grounded	$C_{cb}$	-	0.26	-	pF
Collector emitter capacitance $V_{CE} = 3\text{ V}$ , $f = 1\text{ MHz}$ , $V_{BE} = 0$ , base grounded	$C_{ce}$	-	0.45	-	
Emitter-base capacitance $V_{EB} = 0.5\text{ V}$ , $f = 1\text{ MHz}$ , $V_{CB} = 0$ , collector grounded	$C_{eb}$	-	1.3	-	
Minimum noise figure $I_C = 10\text{ mA}$ , $V_{CE} = 3\text{ V}$ , $f = 1.8\text{ GHz}$ , $Z_S = Z_{Sopt}$ $I_C = 10\text{ mA}$ , $V_{CE} = 3\text{ V}$ , $f = 6\text{ GHz}$ , $Z_S = Z_{Sopt}$	$NF_{min}$	-	0.8	-	dB
		-	1.9	-	
Power gain, maximum available <sup>1)</sup> $I_C = 80\text{ mA}$ , $V_{CE} = 3\text{ V}$ , $Z_S = Z_{Sopt}$ , $Z_L = Z_{Lopt}$ , $f = 1.8\text{ GHz}$ $f = 6\text{ GHz}$	$G_{ma}$	-	21.5	-	
		-	11	-	
Transducer gain $I_C = 80\text{ mA}$ , $V_{CE} = 3\text{ V}$ , $Z_S = Z_L = 50\text{ }\Omega$ , $f = 1.8\text{ GHz}$ $f = 6\text{ GHz}$	$ S_{21e} ^2$	15	17.5	-	dB
		-	7.5	-	
Third order intercept point at output <sup>2)</sup> $V_{CE} = 3\text{ V}$ , $I_C = 80\text{ mA}$ , $f = 1.8\text{ GHz}$ , $Z_S = Z_L = 50\text{ }\Omega$	$IP3$	-	31	-	dBm
1dB compression point at output $I_C = 80\text{ mA}$ , $V_{CE} = 3\text{ V}$ , $Z_S = Z_L = 50\text{ }\Omega$ , $f = 1.8\text{ GHz}$	$P_{-1dB}$	-	17.5	-	

$$^1G_{ma} = |S_{21e} / S_{12e}| (k - (k^2 - 1)^{1/2})$$

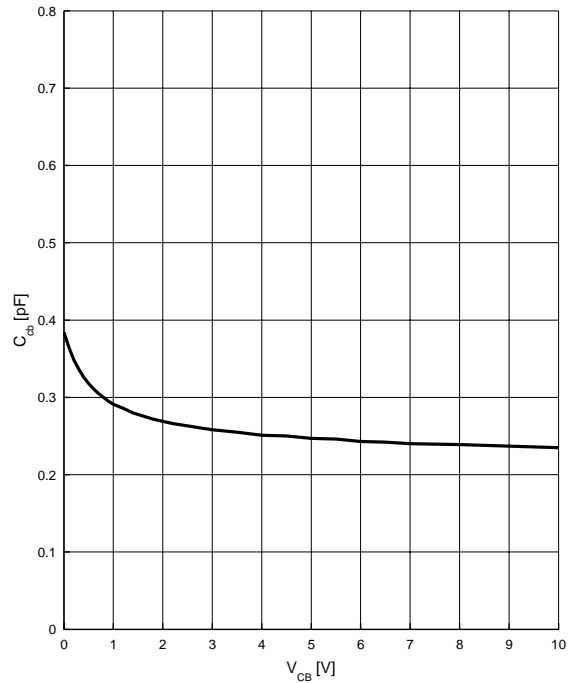
<sup>2</sup>IP3 value depends on termination of all intermodulation frequency components.

Termination used for this measurement is 50Ω from 0.1 MHz to 6 GHz

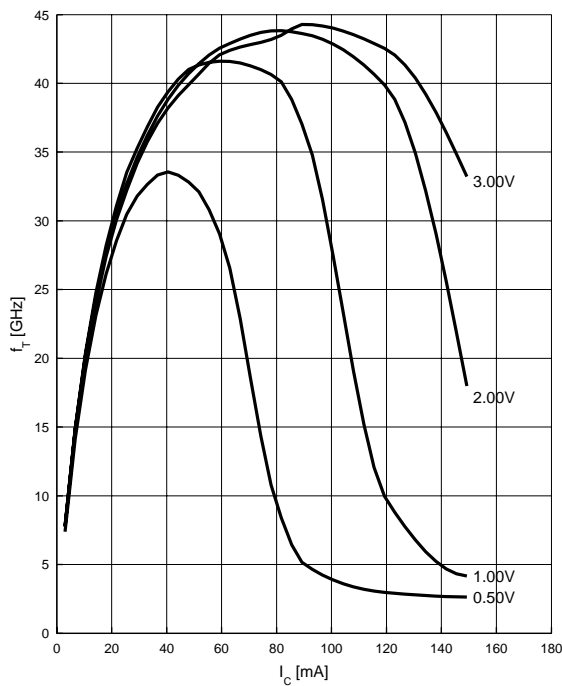
**Total power dissipation  $P_{\text{tot}} = f(T_S)$**



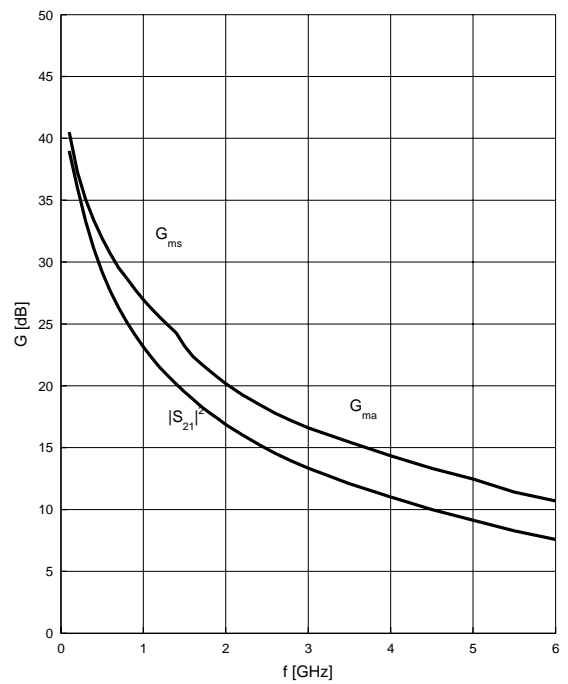
**Collector-base capacitance  $C_{\text{cb}} = f(V_{\text{CB}})$**   
 $f = 1 \text{ MHz}$



**Transition frequency  $f_T = f(I_C)$**   
 $V_{\text{CE}} = \text{parameter in V}, f = 1 \text{ GHz}$



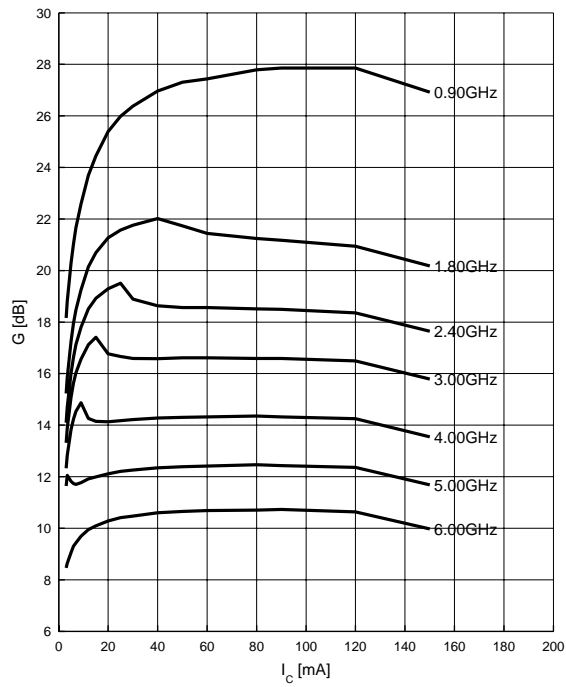
**Power gain  $G_{\text{ma}}, G_{\text{ms}} = f(f)$**   
 $V_{\text{CE}} = 3 \text{ V}, I_C = 80 \text{ mA}$



**Power gain  $G_{ma}$ ,  $G_{ms} = f(I_C)$**

$V_{CE} = 3\text{ V}$

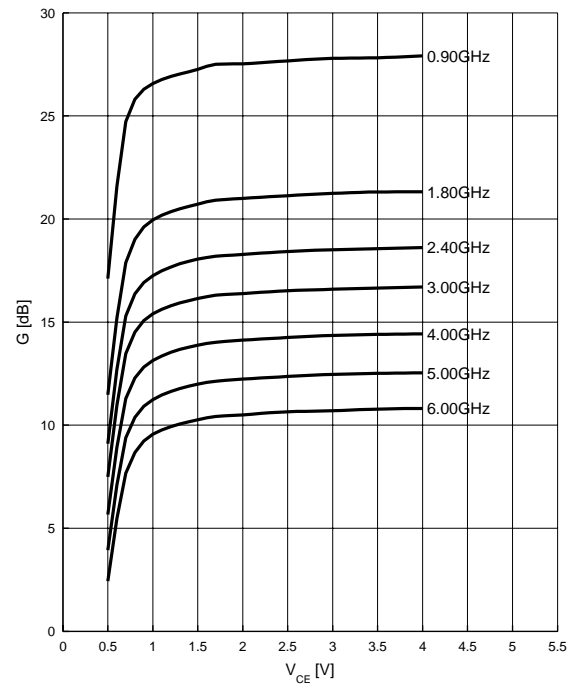
$f = \text{parameter in GHz}$



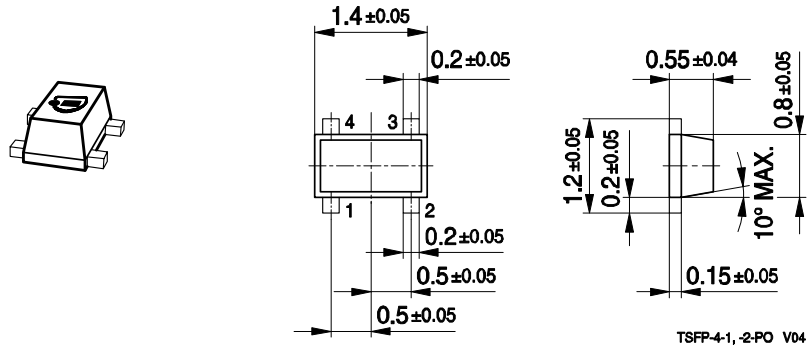
**Power gain  $G_{ma}$ ,  $G_{ms} = f(V_{CE})$**

$I_C = 80\text{ mA}$

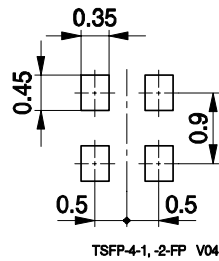
$f = \text{parameter in GHz}$



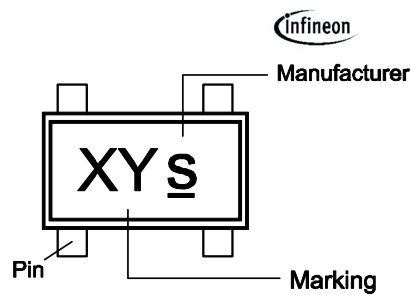
### Package Outline



### Foot Print

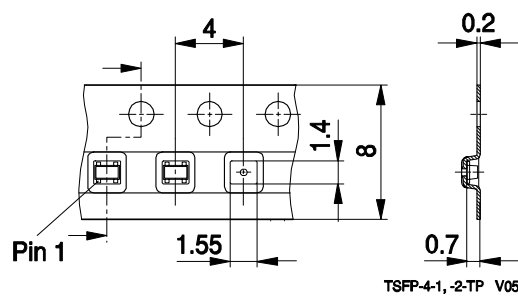


### Marking Layout (Example)



### Standard Packing

Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel



**Edition 2009-11-16**

**Published by  
Infineon Technologies AG  
81726 Munich, Germany**

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